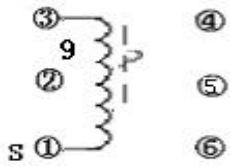
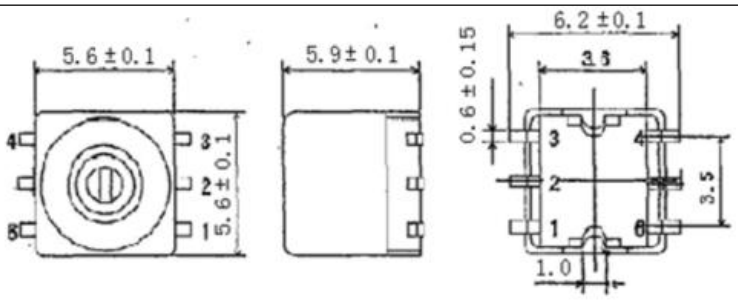
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Specification Sheet

Customer Name	XXXX	CUST P/N	A638AN-0162Z
Approval No.	PD	Temstron P/N	TS-A638AN-0162Z
Lot No.		Date	2026.10.16
Series	SMD	Version	A1
(1) Connection	(2) Size Diagram（Unit：MM）		





(3) Winding Info		(4) Electric Characteristics		
Items	N1	Frequency Variable	30 MHz	L_{13}：680nH±5% (min)
Winding	1-3	Unloaded(Q)		50±20% (Min)
Turns	9Ts	L location		1-3
Wire	2UEW∅0.08	Capacity(out)		
Color		Torque	45-300g/CM	
Print		Remark		
Operation Temp	-25℃～+85℃	Operation Humidity	25%～85%	
Storage Temp	-40℃～+70℃	Storage Humidity	45%～75%RH	
Note				

(5) Testing Data

Test Frequency	30 MHz	Test Voltage	
Test Temperature	23℃	Relative Humidity	65%
Test Equipment	QBG-3E	Quantity	10PCS

Electrical Character: L13：680nH±5%(min)　Q: 50±20%(min)

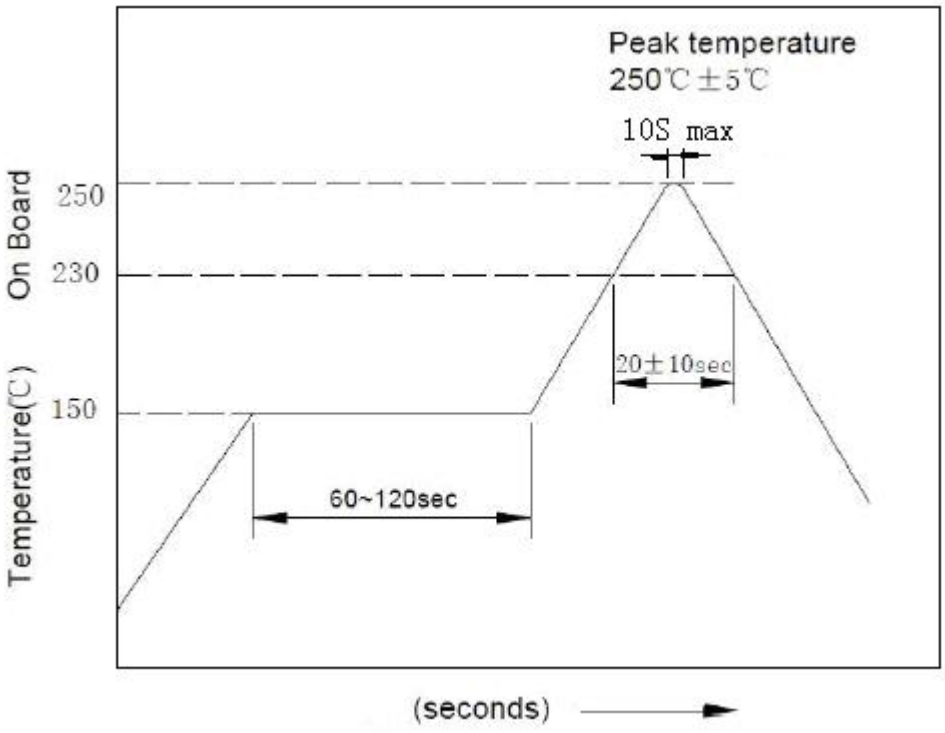
ITEM	L-Max.	L-Min	Q			ITEM	L-Max.	L-Min	Q		
1	779	579	42			6	779	579	44		
2	780	580	43			7	778	578	43		
3	781	581	44			8	781	581	42		
4	776	581	44			9	780	580	42		
5	775	580	43			10	779	580	43		
						Average	778.8	579.9	43		

Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

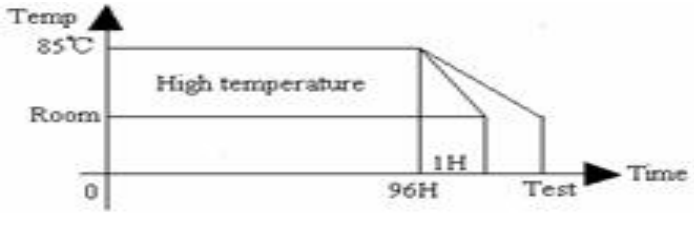
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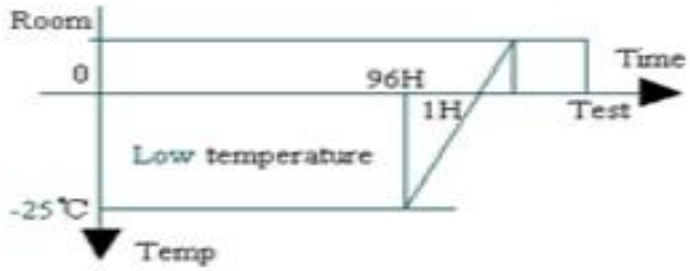
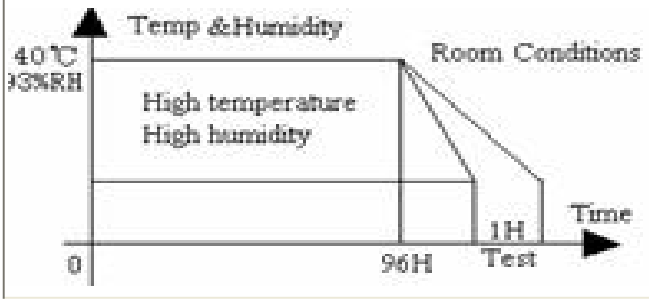
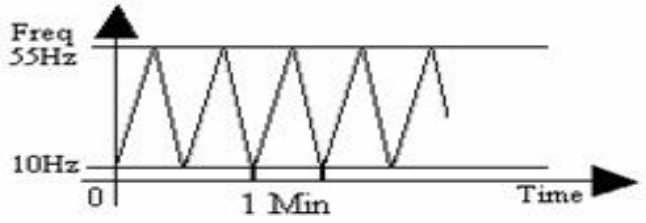
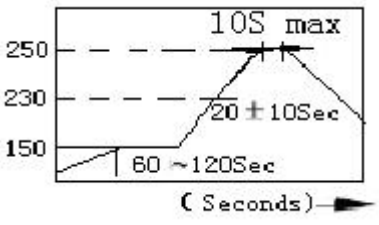
Recommended Soldering Conditions
Reflow Soldering

- Under 350 Degrees, Within 3 seconds, 2 Rounds -



Stability and Test Conditions

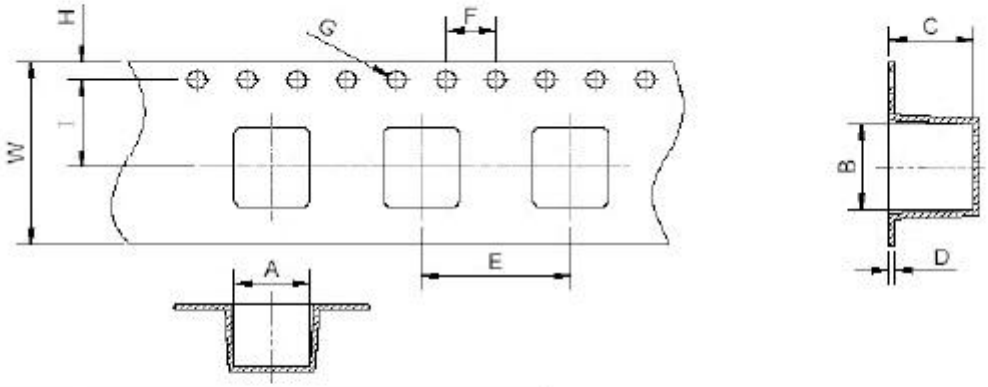
Item	Requirement	Test Method
MIL-STD-202G Method 108A *High Temperature Storage Test	1. No obvious appearance defects 2.Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	Temp:85±2℃; Time:96±2 hours, set the samples in room temp for 1 hour, test within 2 hours 

IEC 68-2-1A 6.1 6.2 *Low Temperature Storage Test	1. No obvious appearance defects 2.Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	Temp:-25±2℃; Time:96±2hours, set the samples in room temp for 1 hour, test within 2 hours. 
MIL-STD-202G Method 103B *Humidity Test	1. No obvious appearance defects 2. Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	1. Dry the samples in 40±5℃ temp condition for 24 hours 2. Test after drying 3. Expose: Temp 40±2℃,Humidity 93±3%RH, for 96±2 hours 4. Test in the chamber after exposing 5. Set the samples in room temp for 1 hour, test within 2 hours. 
MIL-STD-202G Method 208H IPC-J-STD-002B * Solderability Test	95% solder coverage	1. Immerse the solder in the flux, then immerse the solder into 245±5℃ lead-free solder furnace for 5 seconds 2. To solder: Sn(63)/Pb(37) 3. Flux: rosin
MIL-STD-202G Method 201A *Vibration Test	1. No obvious appearance defects 2.Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	Vibrate along the x, y and z axis with 10-55Hz Vibration rate and 0.75mm amplitude for individually 2 hours (Total 6 hours) 
* Solder heat resistance test	1. Smear soldering paste on circuit board, solder at 350 degrees for 2 times. The Pin won't come off and the bottom won't deform . 2. After soldering the reflow at 250 degrees for 3 seconds, the Pin won't come off and the bottom won't deform	(Reflow) 

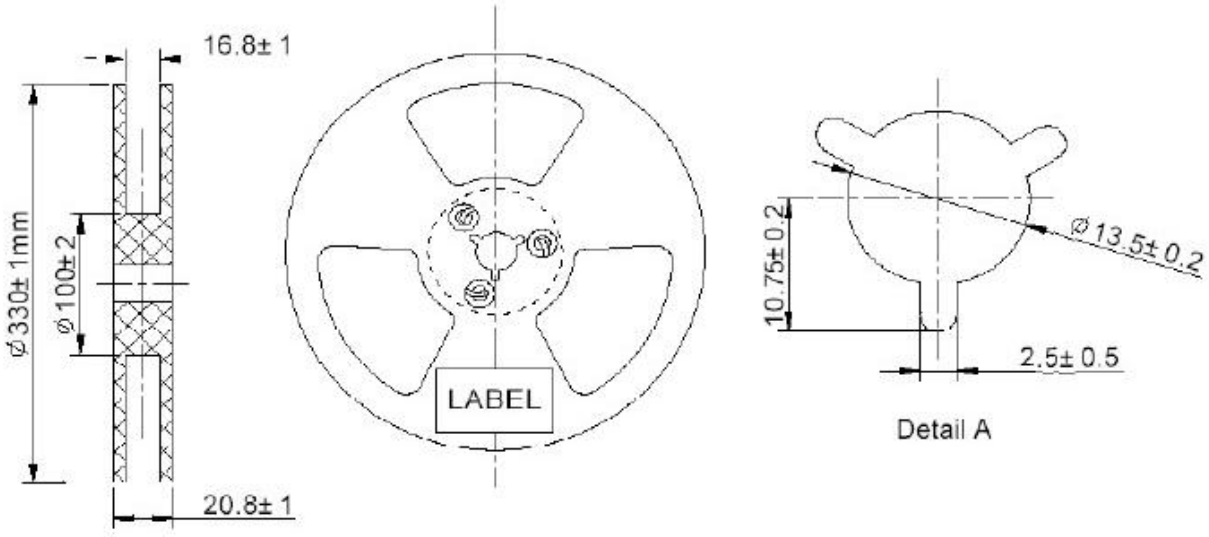
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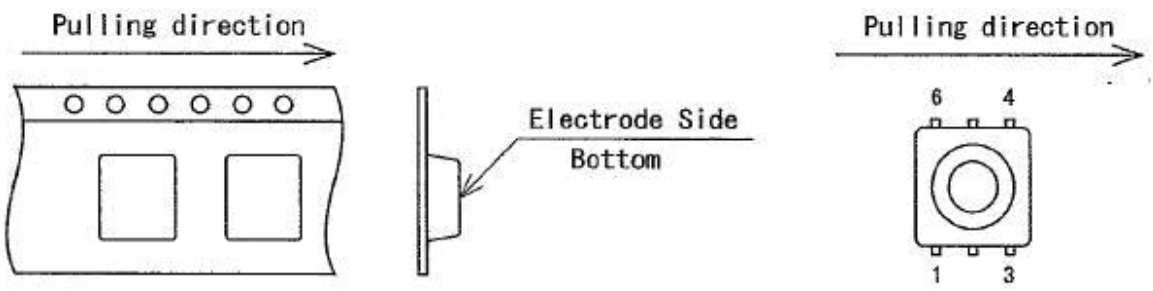
Tape Dimensions

Tape Dimensions



	W=16 $^{\pm 0.3}$ mm		Unit: mm						
ITEM	A	B	C	D	E	F	G	H	I
DIM	6.56	8.0 $^{\pm 0.2}$	6.51	0.5 $^{\pm 0.05}$	12 $^{\pm 0.2}$	4.0 $^{\pm 0.1}$	1.5 $^{\pm 0.1}$	1.75 $^{\pm 0.1}$	7.5 $^{\pm 0.2}$





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Package

